

REFERENCE SPECIFICATIONS	
Product Name	8.9"WQXGA

Approval Signature

Accepted by: _____

Date: _____

Proposed by: _____

Japan Display Inc.

RECORD OF REVISIONS

Date	Sheet No.	Summary
		Initial release (Ver01)

3. GENERAL DATA

3.1 LCM

(1) Part Name	8.9"WQXGA
(2) Module Dimensions	200.9 (H) mm × 132.1 (V) mm × 1.82 (t) mm (Excluding I/F-FPC and electronic components)
(3) Active Area Dimensions	192.0 (H) mm × 120.0 (V) mm
(4) Pixel Pitch	0.075 (H) mm × 0.075 (V) mm
(5) Resolution	2560 × 3 (R,G,B) (H) × 1600 (V) dots
(6) Color Pixel Arrangement	RGB Vertical Stripe
(7) Display Mode	Transmissive Type, Normally Black Mode, In-Plane Switching Mode
(8) Number of Colors	16,777,216 Colors
(9) Viewing Direction	-
(10) Backlight	Light Emitting Diode (LED), 36 LEDs in linear connection Backlight current : 20mA / LED (typ)
(11) Weight	78g (typ)
(12) Power Supply Voltage	VBAT = 3.3V
(13) Interface I/O power supply	VDDIO = 1.8V The same voltage as "H" level of a customer's interface signal must be supplied to VDDIO.
(14) LCD Driver IC	R69429 x2pcs (Renesas SP drivers Inc.)
(15) Interface	MIPI-DSI Command/Video mode (4Lane x 2Port)
(16) Method of Inversion	Column Inversion
(17) Surface Treatment	Hard coat

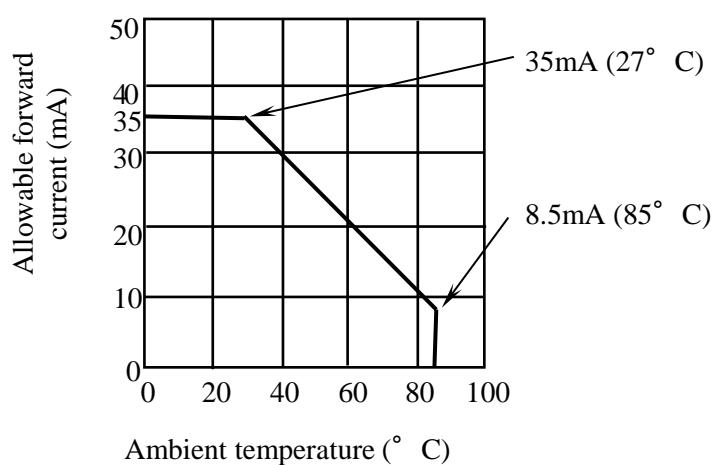
4. ABSOLUTE MAXIMUM RATINGS

4.1 ELECTRICAL ABSOLUTE MAXIMUM RATINGS OF LCD

GND=0 V, Ta=25°C

Item	Symbol	Min	Max	Unit	Note
Power Supply for Interface	VDDIO	-0.3	4.6	V	(1)
Power Supply for DC/DC converter	VBAT	-0.3		V	(1)
Input Voltage	V _i	-0.3	VDDIO+0.3	V	(2)
LED Reverse Voltage	V _R	-	5	V	
LED Forward Current	I _{LED}	-	Note (3)	mA	per LED
Static Electricity	-	-	±2	kV	(4)

- Notes (1) Keep all Voltages no lower than GND.
 (2) Applies to the RESET pin.
 (3) Ambient Temperatures vs. Allow able Forward Current.



- (4) 100 pF - 1.5 kohm, 25°C-70%RH

Static electricity discharge is to be aimed at the center of the active area.

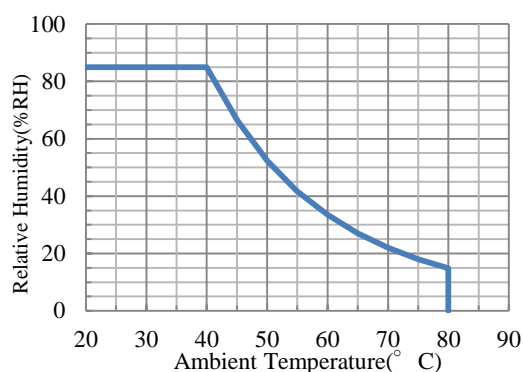
4.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS

Item	Operating		Non-Operating Note(3)		Remarks
	Min	Max	Min	Max	
Ambient Temperature	-20°C	60°C	-20°C	65°C	Note (2)
Humidity	Note (1)		Note (1)		No condensation
Corrosive Gas	Not Acceptable		Not Acceptable		

Notes (1) $T_a \leq 40^\circ\text{C}$ 85%RH max.

$T_a > 40^\circ\text{C}$ Absolute humidity must be lower than the humidity of 85%RH at 40°C .

No dew condensation is allowed.



- (2) Background color slightly changes depending on ambient temperature and viewing angle.
The temperature for operating in the table above apply to operation only.
Visual qualities, such as contrast ratio and response time, to be evaluated at $T_a = 25^\circ\text{C}$ Operating.
- (3) This is not for storing condition. When storing LCM for long term, please follow the condition mentioned in "11.5 STORAGE".

5. ELECTRICAL CHARACTERISTICS

LCD Module

GND=0V, Ta=25°C

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Power Supply Voltage for Logic and Analog	VBAT	-	3.0	3.3	4.5	V	-
Power Supply Voltage for I/O Interface	VDDI	-	1.7	1.8	1.9	V	-
Input Voltage for Logic Circuits	Vi	"H" level	$0.70 \times VDDIO$	-	VDDIO	V	(1),(2)
		"L" level	0	-	$0.30 \times VDDIO$		
Input Voltage for EN	Vi	"H" level	$0.90 \times VDDIO$	-	VDDIO	V	(1)
		"L" level	0	-	$0.10 \times VDDIO$		
Output Voltage for Logic Circuits	Vo	"H" level	$0.80 \times VDDIO$	-	-	V	(1),(2)
		"L" level	-	-	$0.20 \times VDDIO$		
Power Consumption	POWER	All White	-	(230)		mW	(3),(4)

Notes (1) VDDIO = 1.7V to 1.9V

(2) Input : RESET, DBIST

Output : PWM, TE

(3) VDDIO=1.7V~1.9V, VBAT=3V~4.5V, Column inversion mode.

Display image : ALL White

(4) Operation Mode : MIPI-DSI Command mode, LCM Display frame rate = 60.37~66.72fps
MIPI-DSI Data and Clock lane = LP11

6. OPTICAL CHARACTERISTICS

LCD (BACKLIGHT ON)

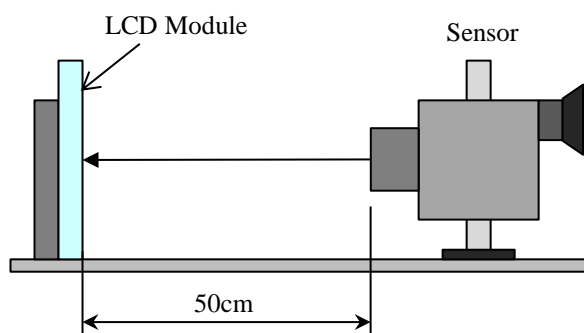
Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Notes
Brightness	B	$\varphi=0^\circ, \theta=0^\circ$		(500)	-	cd/m ²	(1),(2)
Contrast Ratio	CR	$\varphi=0^\circ, \theta=0^\circ$		(1200)	-	-	(3)

Measurement Conditions

Measurement environment : Dark room
 Ambient temperature : Ta=25°C
 Sequence : Refer to Item 8.5.2
 Power supply voltage : VDDIO=1.8V, VBAT=3.3V
 Backlight current : I_{LED}=20mA

Notes (1) Definition of Brightness "B"

(2) Display image for measurement : All White



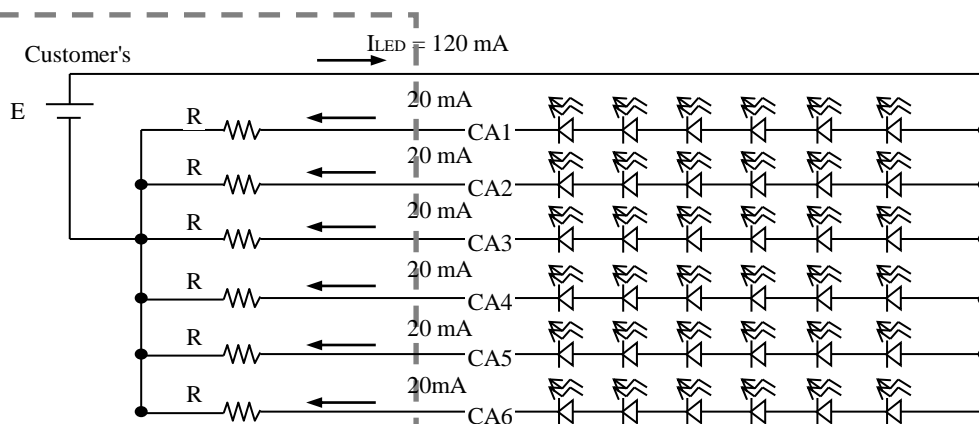
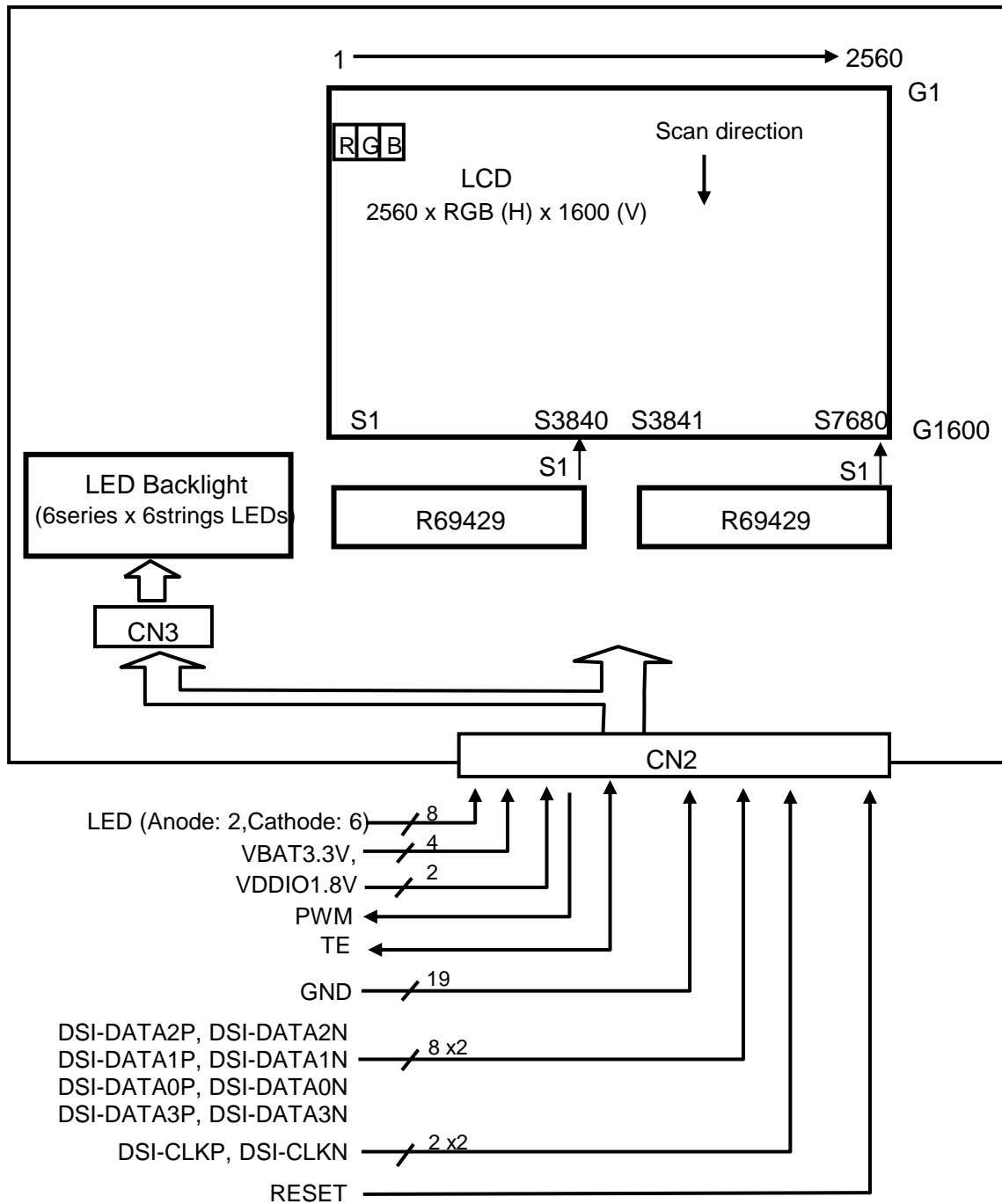
Sensor : KONICA MINOLTA CS-1000 or equivalent

Measurement point: Center of LCD's active area

(3) Definition of Contrast "CR"

$$CR = \frac{\text{Brightness when displaying White raster}}{\text{Brightness when displaying Black raster}}$$

7. BLOCK DIAGRAM



8. INTERFACE

8.1 INTERNAL PIN CONNECTION

Pin No.	Signal	I/O	Function	Driver's Signal name
1	GND	-	GND	-
2	GND	-	GND	-
3	GND	-	GND	-
4	V_LED_C6	-	GND for LED	-
5	V_LED_C5	-	GND for LED	-
6	V_LED_C4	-	GND for LED	-
7	V_LED_C3	-	GND for LED	-
8	V_LED_C2	-	GND for LED	-
9	V_LED_C1	-	GND for LED	-
10	V_LED_A	-	Power Supply for LED	-
11	V_LED_A	-	Power Supply for LED	-
12	N.C	-	Non connect	-
13	GND	-	GND	-
14	PWM	O	Control Signal for LED Brightness	LEDPWM
15	TE	O	Tearing Effect Output	TE
16	GND	-	GND	-
17	DSI_R-DATA-2P	I	Positive MIPI Data2 Input	DATA2P
18	DSI_R-DATA-2N	I	Negative MIPI Data2 Input	DATA2N
19	GND	-	GND	-
20	DSI_R-DATA-1P	I	Positive MIPI Data1 Input	DATA1P
21	DSI_R-DATA-1N	I	Negative MIPI Data1 Input	DATA1N
22	GND	-	GND	-
23	DSI-CLKP	I	Positive MIPI Clock Input	CLKP
24	DSI-CLKN	I	Negative MIPI Clock Input	CLKN
25	GND	-	GND	-
26	DSI_R-DATA-0P	I/O	Positive MIPI Data0 Input/Output	DATA0P
27	DSI_R-DATA-0N	I/O	Negative MIPI Data0 Input/Output	DATA0N
28	GND	-	GND	-
29	DSI_R-DATA-3P	I	Positive MIPI Data3 Input	DATA3P
30	DSI_R-DATA-3N	I	Negative MIPI Data3 Input	DATA3N
31	GND	-	GND	-
32	EN	I	Enable Pin to Operate DC/DC converter	-

Continue to next page

Pin No.	Signal	I/O	Function	Driver's Signal name
33	N.C	-	Non connect	-
34	VBAT	-	Power Supply for DC/DC converter	-
35	VBAT	-	Power Supply for DC/DC converter	-
36	VBAT	-	Power Supply for DC/DC converter	-
37	VBAT	-	Power Supply for DC/DC converter	-
38	N.C	-	Non connect	-
39	VDDIO	-	Power Supply for I/O Interface and logic	-
40	VDDIO	-	Power Supply for I/O Interface and logic	-
41	GND	-	GND	-
42	DBIST(GND)	I	GND (Enable pin to Generate Self Refresh Image)	DBIST
43	TE_S	O	Non connect (Test pin for LCD Module supplier)	-
44	GND	-	GND	-
45	RESET	I	Reset Signal	RESX
46	GND	-	GND	-
47	DSI_L-DATA-2P	I	Positive MIPI Data2 Input	DATA2P
48	DSI_L-DATA-2N	I	Negative MIPI Data2 Input	DATA2N
49	GND	-	GND	-
50	DSI_L-DATA-1P	I	Positive MIPI Data1 Input	DATA1P
51	DSI_L-DATA-1N	I	Negative MIPI Data1 Input	DATA1N
52	GND	-	GND	-
53	DSI-CLKP	I	Positive MIPI Clock Input	CLKP
54	DSI-CLKN	I	Negative MIPI Clock Input	CLKN
55	GND	-	GND	-
56	DSI_L-DATA-0P	I/O	Positive MIPI Data0 Input/Output	DATA0P
57	DSI_L-DATA-0N	I/O	Negative MIPI Data0 Input/Output	DATA0N
58	GND	-	GND	-
59	DSI_L-DATA-3P	I	Positive MIPI Data3 Input	DATA3P
60	DSI_L-DATA-3N	I	Negative MIPI Data3 Input	DATA3N
61	GND	-	GND	-

LCM Connector :FH36W-61S-0.3SHW(50)(Header) (HIROSE)

8.2 LCM Control sequence

8.2.1 LCM Circuit configuration

H:2560RGB x V:1600

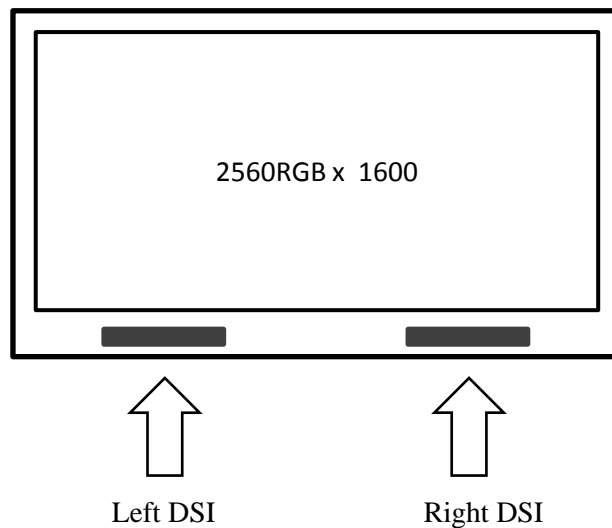
R69429, 2Chip

w/RAM

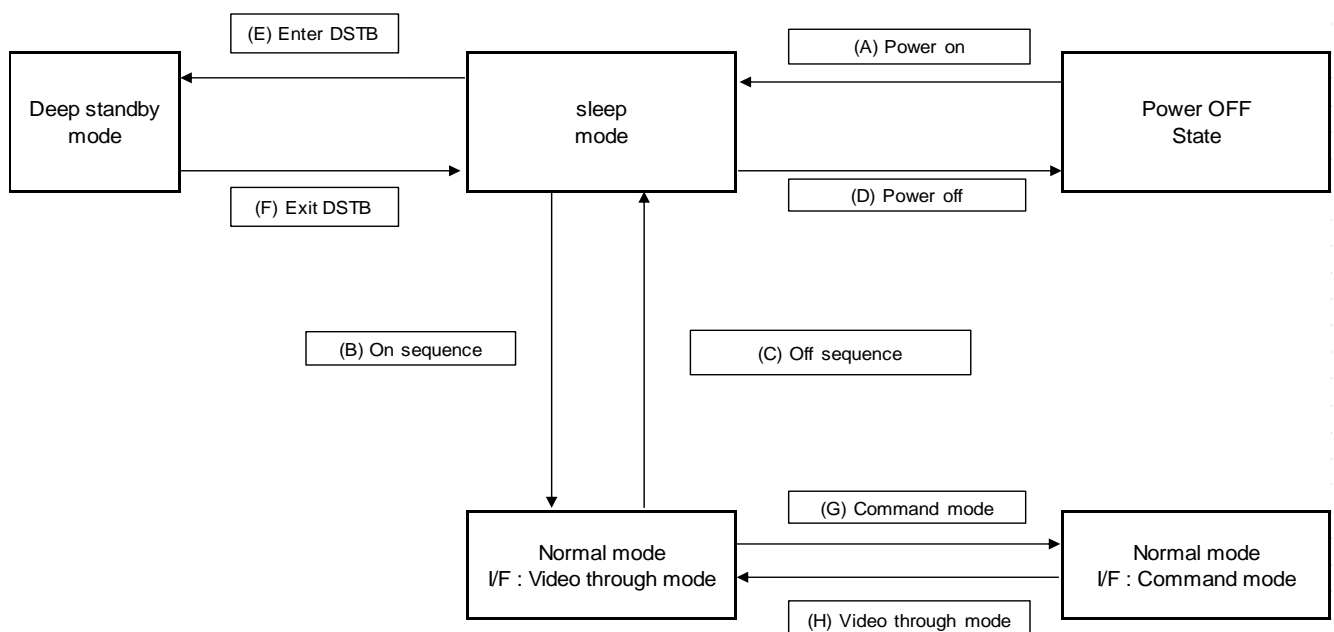
Mipi-DSI 4lane x 2port

Power Supply : VDDIO=1.8v(typ), VBAT=3.3v(typ)

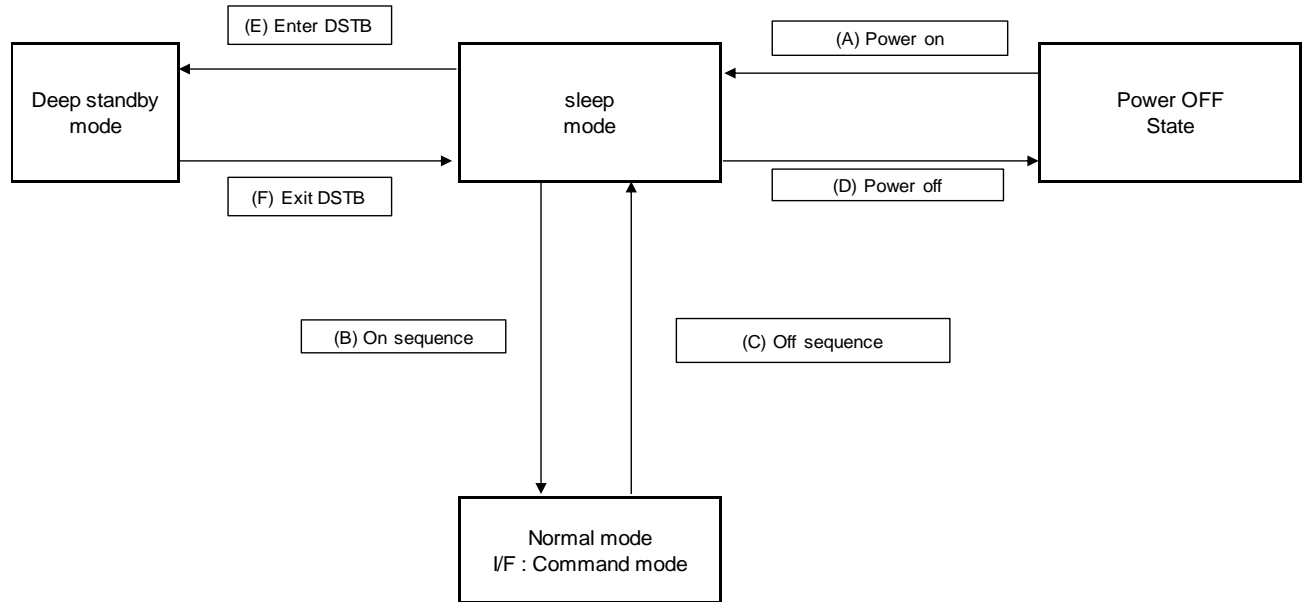
(The DCDC on flex generates R69429's VSP/VSN from VBAT.)



8.2.2 Video through mode and Command mode Status flow



8.2.3 Command mode Status flow



8.2.4 Power Supply Sequence

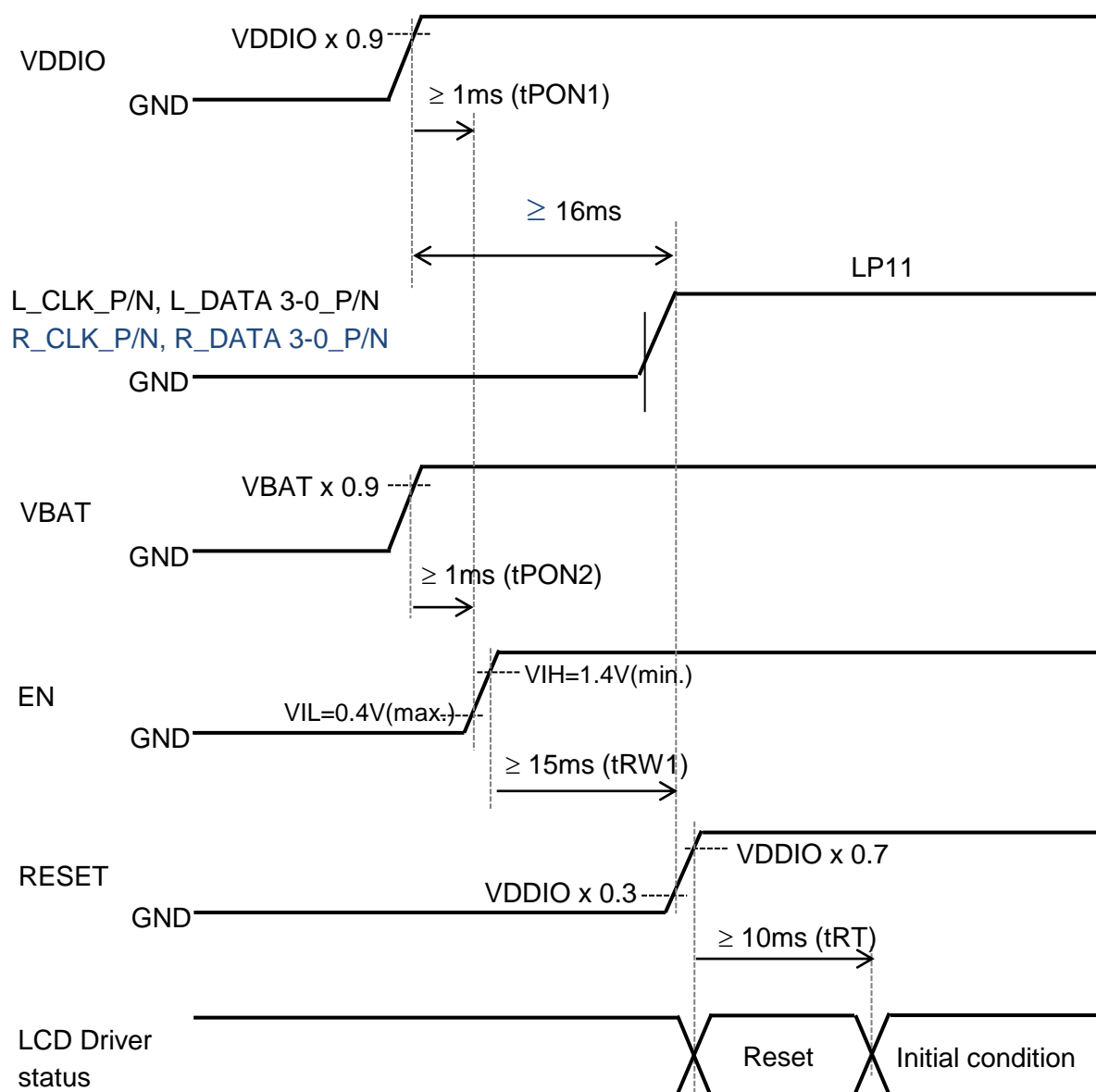
Note1) Make sure that the following relationship are satisfied : $VDDIO \geq \text{RESET}$,
 $VDDIO \geq \text{MIPI-DSI signals}$.

Note 2) Reset Timing Characteristics

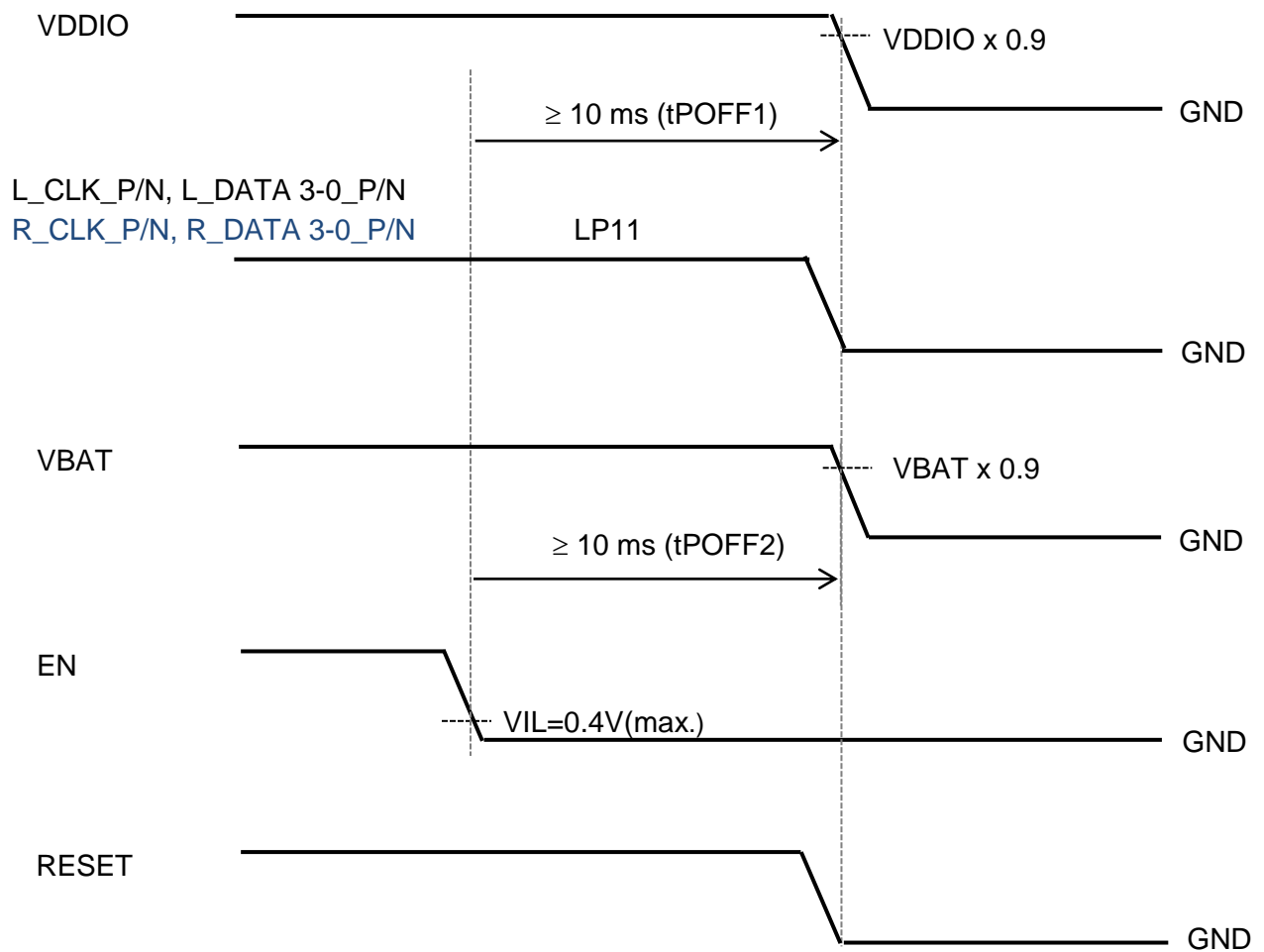
(Power supply voltage and temperature range are ruled by the LCM delivery)

Item	Symbol	Unit	Test condition	Min.	Max.
VDDIO-EN delay time	tPON1	ms	Power On	1	-
3.3V-EN delay time	tPON2	ms	Power On	1	-
Reset low-level width	tRW1	ms	Power On	15	-
Reset time	tRT	ms	Power On	10	-
EN-VDDIO delay time	tPOFF1	ms	Power Off	10	-
EN-3.3V delay time	tPOFF2	ms	Power Off	10	-

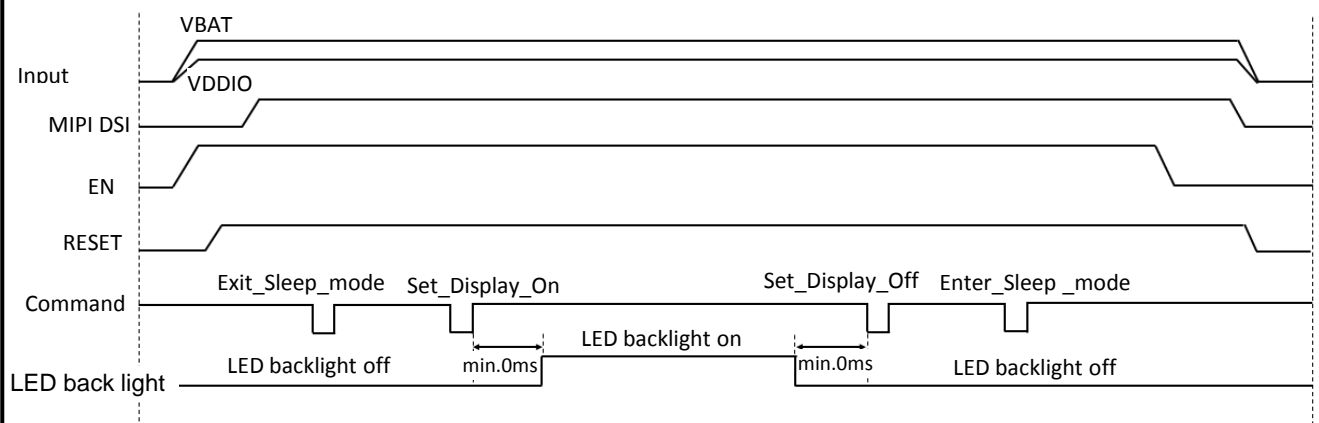
8.2.5 Power On sequence



8.2.6 Power Off sequence



LED Power On/Off sequence



8.2.7 Video through mode and Command mode Sequence

(A) Power on

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
POWER OFF STATE						
↓						
PWR supply on					VDDIO, VBAT on	
wait 1ms						
EN L → H					VSP,VSN on	
wait 15ms						
RESET L → H					RESET L → H	
wait 10ms						
(EN H → L)					VSP,VSN off	(*)Can skip "VSP/VSN off" in case of going to normal mode without staying sleep status.
(wait 10ms)						
↓						
SLEEP MODE						

(B) On sequence

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
EN L → H					VSP,VSN on	(*)
wait 20ms						(*)
command	05	01	-	-	L/R soft reset	
wait 5ms						
command	15	3A	1	77	L/R set pixel format	
command	39	2A	1	00	L/R set column address	
			2	00		
			3	04		
			4	FF		
command	39	2B	1	00	L/R set page address	
			2	00		
			3	06		
			4	3F		
command	15	35	1	00	R set tear on	Recommend monitoring TE timing due to the restriction in 2chip system, for details, refer "Restriction on command timing"
command	39	44	1	00	R set tear scanline	
			2	00		
command	15	51	1	FF	L/R write_display_brightness	
command	15	53	1	24	L/R write_control_display	
command	15	55	1	00	L/R write_adaptive_brightness_control C[1:0] = 0x00 : ACO • CABC Off	Please use Auto Contrast Optimization (ACO) function and Content Adaptive Brightness Control (CABC) function by C[1:0] register, changing.
			1	01	L/R write_adaptive_brightness_control C[1:0] = 0x01 : ACO On	
			1	02	L/R write_adaptive_brightness_control C[1:0] = 0x02 : CABC On Max. Backlight reduction ratio : ~33% setting	
			1	03	L/R write_adaptive_brightness_control C[1:0] = 0x03 : CABC On Max. Backlight reduction ratio : ~54% setting	
command	05	11	-	-	L/R exit sleep mode	
wait 120ms						
command	23	B0	1	00	L/R MCAP	This command is inputted for change of LEDPWM clock frequency. When using [C[1:0] = 0x00 : ACO • CABC Off] and [C[1:0] = 0x01 : ACO On], it is not necessary to input this command.
command	29	CE	1	7D	L/R Back Light Control 4	(1)This command is inputted for change of LEDPWM clock frequency. When using [C[1:0] = 0x00 : ACO • CABC Off] and [C[1:0] = 0x01 : ACO On], it is not necessary to input this command. (2)Please optimize a LEDPWM clock frequency by PWM_DIV [7:0] and PWM_CYCLE[7:0] according to the characteristic of the LED driver used in your company.
			2	40		
			3	48		
			4	56		
			5	67		
			6	78		
			7	88		
			8	98		
			9	A7		
			10	B5		
			11	C3		
			12	D1		
			13	DE		
			14	E9		
			15	F2		
			16	FA		
			17	FF		
			18	04	PWM_DIV[7:0]	
			19	00	PWM_CYCLE[7:0]	
Transferring video mode packets (> 1 frame)						
Note) it is necessary to input DSICLK / VSYNC packet / HSYNC packet, before setting B3h register.						
command	23	B0	1	00	L/R MCAP	
command	29	B3	1	14	L/R Interface setting	Video through mode setting
command	23	B0	1	03	L/R MCAP	
command	05	29	-	-	L/R set display on	
↓						
NORMAL MODE, I/F : Video through mode						

LCM Control Sequence (Continued)

(1)These CABC setting values are our proposal values.

It optimizes based on the evaluation result of your company.

CABC On -33% :Max. Backlight power reduction rate -33% setting

CABC On -54% :Max. Backlight power reduction rate -54% setting

(2)LEDPWM frequency calculation formula

LEDPWM frequency = $f_{OSC2} / (PWM_{DIV} + 1) / (PWM_CYCLE + 255)$

$f_{OSC2} spec. = 26.6MHz(min.) - 28MHz(typ.) - 29.4MHz(max.)$

(3)LEDPWM frequency default setting :

Command 0xCE, PWM_DIV[7:0]=0x04, PWM_CYCLE[7:0]=0x00

LEDPWM frequency = $28MHz (typ.) / (4+1) / (0+255) = 21.96kHz(typ.)$

(c) Off sequence

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
NORMAL MODE, 1F : Video through mode						
↓						
command	05	28	-	-	L/R	set display off
wait 20ms						
command	05	10	-	-	L/R	enter sleep mode
wait 80ms						
EN H -> L						VSP,VSN off
wait 10ms						
↓						
SLEEP MODE						

(D) Power off

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
RESET H->L						
PWR supply off						VDDIO, VBAT off
↓						
POWER OFF STATE						

(E) Enter DSTB

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
command	23	B0	1	00	L/R	MCAP
command	23	B1	1	01	L/R	DSTB=1
↓						
DSTB MODE						

(F) Exit DSTB

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
DSTB MODE						
↓						
RESET H -> L						
wait 10ms						
EN L -> H						VSP,VSN on
wait 20ms						
RESET L->H						RESET L->H
wait 10ms						
(EN H -> L)						VSP,VSN off
(wait 10ms)						(*)Can skip "VSP/VSN off" in case of going to normal mode without staying sleep status.
↓						
SLEEP MODE						

LCM Control sequence (Continued)

(G) Command mode

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
NORMAL MODE, VF : Video through mode						
Triggered by detecting TE="High" Note) Command input in blank period						
command	23	B0	1 00	L/R	MCAP	
command	29	B3	1 0C	L/R	Interface setting	Video capture mode setting
command	23	B0	1 03	L/R	MCAP	
Transferring video mode packets (> 1 frame) Note) it is necessary to input DSICLK / VSYNC packet / HSYNC packet, until 1frame period after setting B3h register.						
NORMAL MODE, VF : Command mode						
Transferring command mode packets						
send image	39	2C/3C		L/R	write memory / write memory continue	

(H) Video through mode

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
NORMAL MODE, VF : Command mode						
Transferring video mode packets Note) it is necessary to input DSICLK / VSYNC packet / HSYNC packet, before setting B3h register.						
Triggered by detecting TE="High" Note) Command input in blank period						
command	23	B0	1 00	L/R	MCAP	
command	29	B3	1 1C	L/R	Interface setting	Video through mode setting
command	23	B0	1 03	L/R	MCAP	
Transferring video mode packets (> 1 frame)						
NORMAL MODE, VF : Video through mode						

MP (J1) ID Code

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
command	06	A1	1 28 2 0A 3 MP Production year and week code	Right	read_DDB_start	

MP (D1) ID Code

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
command	06	A1	1 28 2 0A 3 MP Production year and week code	Right	read_DDB_start	

8.2.8 Command mode Sequence

(A) Power on

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
POWER OFF STATE						
↓						
PWR supply on					VDDIO, VBAT on	
wait 1ms						
EN L->H					VSP, VSN on	
wait 15ms						
RESET L->H					RESET L->H	
wait 10ms						
(EN H->L)					VSP, VSN off	(*)Can skip "VSP/VSN off" in case of going to normal mode without staying sleep status.
(wait 10ms)						
↓						
SLEEP MODE						

(B) On sequence

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
EN L->H					VSP, VSN on	(*)
wait 20ms						(*)
command	05	01	-	L/R	soft reset	
wait 5ms						
command	15	3A	1 77	L/R	set pixel format	
command	39	2A	1 00 2 00 3 04 4 FF	L/R	set column address	
command	39	2B	1 00 2 00 3 06 4 3F	L/R	set page address	
send image	39	2C/3C		L/R	write memory / write memory continue	
command	15	35	1 00	R	set tear on	Recommend monitoring TE timing due to the restriction in 2chip system, for details, refer "Restriction on command timing"
command	39	44	1 00 2 00	R	set tear scanline	
command	15	51	1 FF	L/R	write_display_brightness	
command	15	53	1 24	L/R	write_control_display	
command	15	55	1 00	L/R	write_adaptive_brightness_control C[1:0] = 0x00 : ACO · CABC Off	Please use Auto Contrast Optimization (ACO) function and Content Adaptive Brightness Control (CABC) function by C[1:0] register, changing.
			1 01	L/R	write_adaptive_brightness_control C[1:0] = 0x01 : ACO On	
			1 02	L/R	write_adaptive_brightness_control C[1:0] = 0x02 : CABC On Max. Backlight reduction ratio : -33% setting	
			1 03	L/R	write_adaptive_brightness_control C[1:0] = 0x03 : CABC On Max. Backlight reduction ratio : -54% setting	
command	05	11	-	L/R	exit sleep mode	
wait 120ms						
command	23	B0	1 00	L/R	MCAP Off	This command is inputted for change of LEDPWM clock frequency. When using [C[1:0] = 0x00 : ACO · CABC Off] and [C[1:0] = 0x01 : ACO On], it is not necessary to input this command.
command	29	CE	1 7D 2 40 3 48 4 56 5 67 6 78 7 88 8 98 9 A7 10 B5 11 C3 12 D1 13 DE 14 E9 15 F2 16 FA 17 FF 18 04 19 00	L/R	Back Light Control 4	(1)This command is inputted for change of LEDPWM clock frequency. When using [C[1:0] = 0x00 : ACO · CABC Off] and [C[1:0] = 0x01 : ACO On], it is not necessary to input this command. (2)Please optimize a LEDPWM clock frequency by PWM_DIV [7:0] and PWM_CYCLE[7:0] according to the characteristic of the LED driver used in your company.
Deleted from Video through mode sequence						
command	23	B0	1 03	L/R	MCAP On	
Deleted from Video through mode sequence						
command	05	29	-	L/R	set display on	
wait 0ms min.						
LED backlight on						
↓						
NORMAL MODE, I/F : Command mode						

LCM Control Sequence (Continued)

(1) These CABC setting values are our proposal values.

It optimizes based on the evaluation result of your company.

CABC On -33% : Max. Backlight power reduction rate -33% setting

CABC On -54% : Max. Backlight power reduction rate -54% setting

(2) LEDPWM frequency calculation formula

LEDPWM frequency = $f_{OSC2} / (PWMDIV + 1) / (PWM_CYCLE + 255)$

fOSC2 spec. = 26.6MHz(min.) - 28MHz(typ.) - 29.4MHz(max.)

(3) LEDPWM frequency default setting :

Command 0xCE, PWMDIV[7:0]=0x04, PWM_CYCLE[7:0]=0x00

LEDPWM frequency = 28MHz (typ.) / (4+1) / (0+255) = 21.961kHz(typ.)

(c) Off sequence

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment	
NORMAL MODE							
↓							
LED backlight off							
wait 0ms min.							
command	05	28	-	-	L/R	set display off	
wait 20ms							
command	05	10	-	-	L/R	enter sleep mode	
wait 80ms						In Video mode, please continue the input of Vsync packet, Hsync packet, and DSICLK until Off sequence is completed.	
EN H-> L							VSP, VSN off
wait 10ms							
↓							
SLEEP MODE							

(D) Power off

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
RESET H->L						
PWR supply off					VDDIO, VBAT off	
↓						
POWER OFF STATE						

(E) Enter DSTB

sequence	Data Type (hex)	index (hex)	parameters # (hex)	L/R	description	comment
SLEEP MODE						
↓						
command	23	B0	1 00	L/R	MCAP	
command	23	B1	1 01	L/R	DSTB=1	
↓						
DSTB MODE						

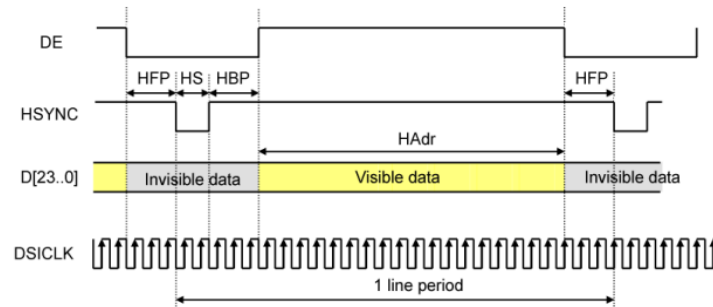
(F) Exit DSTB

sequence	DataType (hex)	index (hex)	parameters # (hex)	L/R	description	comment
DSTB MODE						
<div></div>						
RESET H-> L						
wait 10ms						
EN L-> H					VSP,VSN on	
wait 20ms						
RESET L->H					RESET L->H	
wait 10ms						
(EN H-> L)					VSP,VSN off	(*1)Can skip "VSP/VSN off" in case of going to normal mode without staying sleep status.
(wait 10ms)						
<div></div>						
SLEEP MODE						

8.2.9 Timing restrictions in Video mode

The blanking period is specified for the pixel data transfer to the two chips in Video Mode.

Set 45 ByteClock or less in the time that the pixel data transfer to the slave chip precedes and is behind the pixel data transfer to the master chip.



Item	Symbol	Condition	Unit	Min.
Horizontal front porch	HFP		ByteClock	4lanes:100+ β
Horizontal data start point	-	HS+HBP	ByteClock	45+ α

$$\alpha\beta \leq 45 \text{ ByteClock}$$

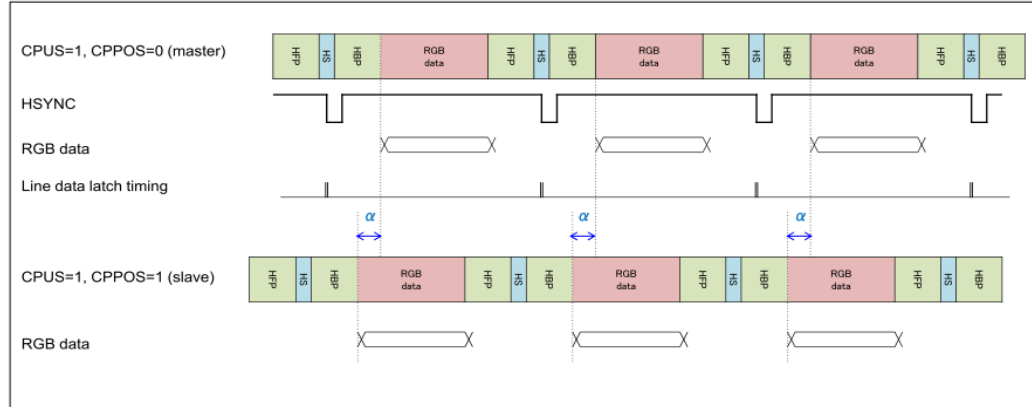
α : Time the pixel data is transferred to the slave chip (CPUS=1, CPPOS=1) precedes time the pixel data is transferred to the master chip (CPUS=1, CPPOS=0)

β : Time the pixel data is transferred to the slave chip (CPUS=1, CPPOS=1) is behind time the pixel data is transferred to the master chip (CPUS=1, CPPOS=0)

1 ByteClock = 4 DSI Clock, 1ByteClock=4/3PixelClock (4 lanes)

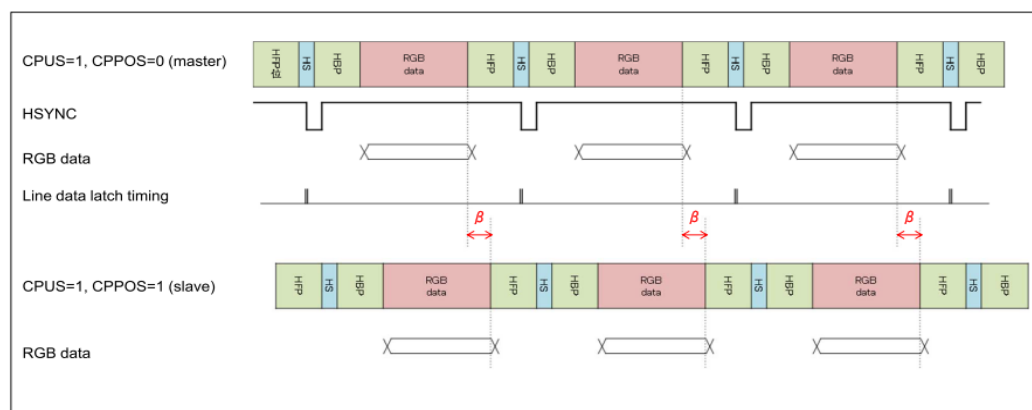
1) Video Access (Pixel Data Transfer to Slave Chip Precedes Pixel Data Transfer To Master Chip)

Add the precursor time α to the HS+HBP (horizontal data start point) setting.



2) Video Access (Pixel Data Transfer to Slave Chip is behind Pixel Data Transfer to Master Chip)

Add the delay time β to the HFP (Horizontal front porch) setting.

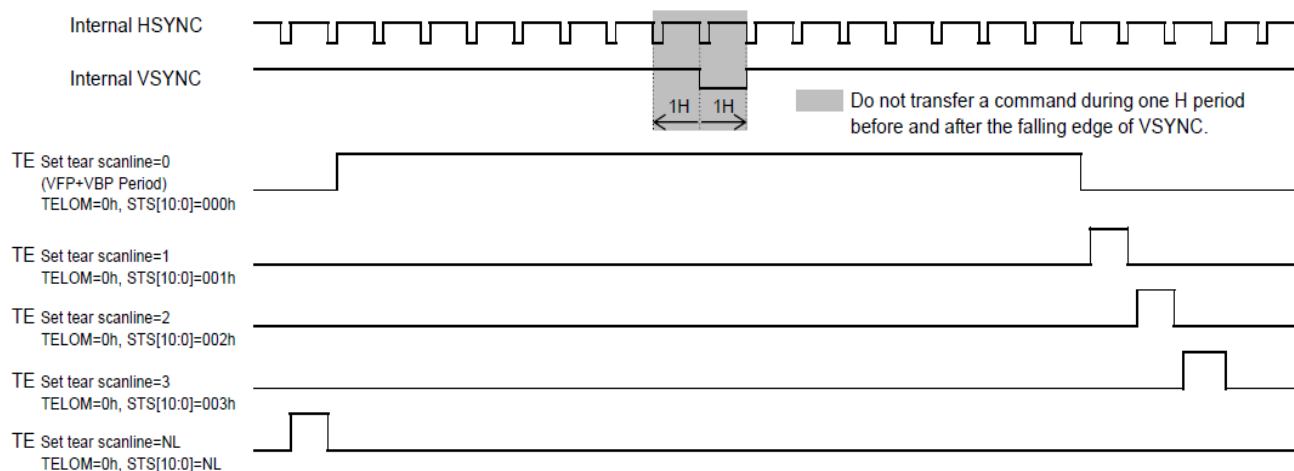


8.2.10 Restriction on command timing (in case of command access)

Timing Restrictions on the transfer command of Two-Chip Structure

When two chips are used (for point-to-point system), the execution of a command in a first chip may be one frame period behind that of a command in a second chip according to the timing that the host transfer a command. Therefore, the transfer command has the following timing restrictions.

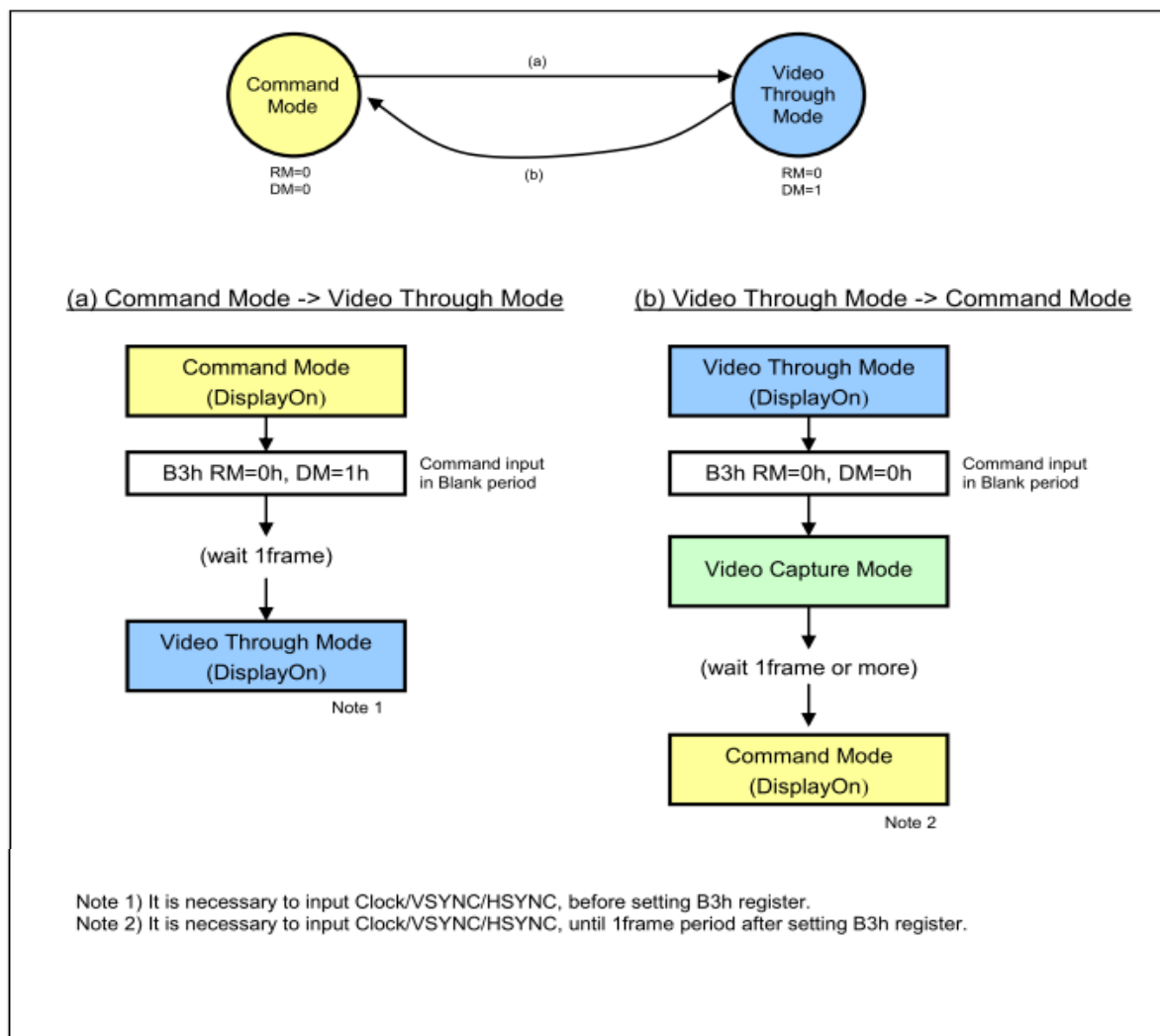
2. Command Access



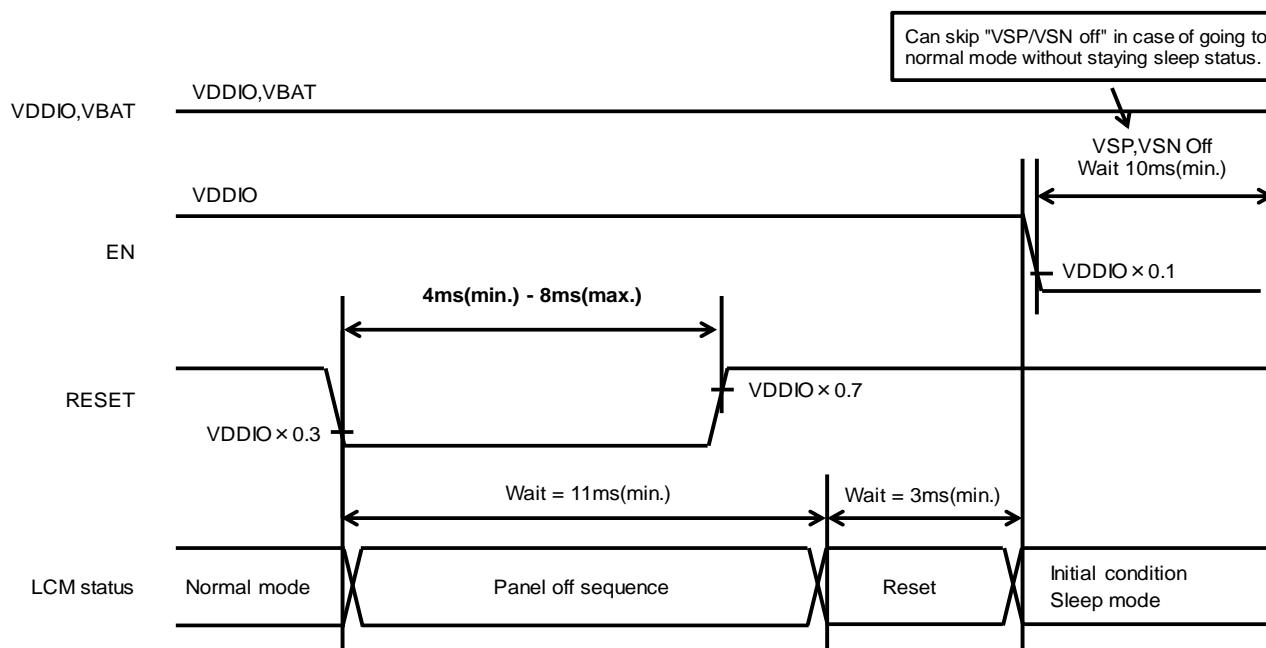
8.2.11 Display mode change in SleepOUT (Display on)

(2) Display mode change in SleepOUT (Display On)

Command Mode and Video Through Mode can be changed while on DisplayOn state via Video Capture Mode. (Case B3h V2CRM bit = 1)

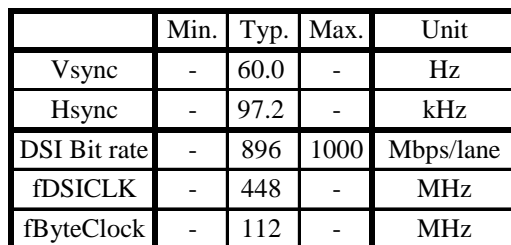


8.2.12 Reset timing spec. during display

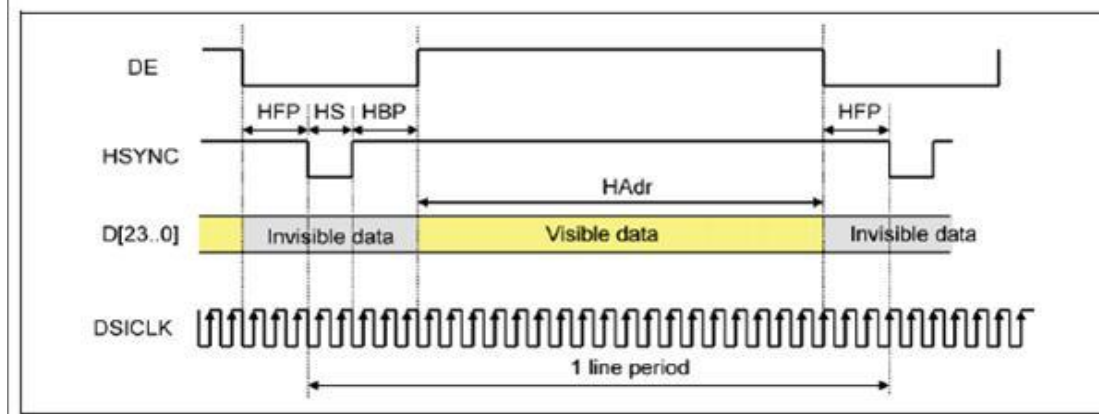


MIPI-DSI Video mode timing chart

2) Vertical Display Timing (Video Mode)



3) Horizontal Display Timing (Video Mode)



8.3 MIPI-DSI Characteristics

8.3.1 DC Characteristics

Item		Symbol	Unit	Test condition	Min.	Typ.	Max.	Note
HS-RX	Differential input high threshold	VIDTH	mV		-	-	70	3
	Differential input low threshold	VIDTL	mV		-70	-	-	3
	Single-ended input low voltage	VILHS	mV		-40	-	-	
	Single-ended input high voltage	VIHHS	mV		-	-	460	
	Common-mode voltage HS receive mode	VCMRX(DC)	mV		70	-	330	1
	Differential input impedance	ZID	Ω		-	100	-	2
LP-RX	Logic 0 input voltage not in ULP State	VIL	mV		-50	-	550	
	Logic 1 input voltage	VIH	mV		880	-	1350	
	I/O leakage current	ILEAK	μA	Vin= -50mV - 1350mV	-10	-	10	
LP-TX	Thevenin output low level	VOL	mV		-50	-	50	
	Thevenin output high level	VOH	V		1.1	1.2	1.3	
	Output impedance of LP Transmitter	ZOLP	Ω		110	-	-	2
CD-RX	Logic 0 contention threshold	VILCD	mV		-	-	200	
	Logic 1 contention threshold	VIHCD	mV		450	-	-	

- Note: 1. $V_{CMRX}(DC) = (V_{DP} + V_{DN}) / 2$
2. Excluding COG resistance (contact resistance and ITO wiring resistance).
3. Minimum 110mV/-110mV HS differential swing is required for display data transfer.

8.3.2 MIPI DSI HS-RX Clock and Data-Clock Specifications

Item	Symbol	Unit	Min.	Typ.	Max.	Note
DSICLK Frequency	fDSICLK	MHz	100	-	500	4
DSICLK Cycle time	tCLKP	ns	1	-	10	
DSI Data Transfer Rate	tDSIR	Mbps	200	-	1000	4
Data to Clock Setup Time	tSETUP	UI	0.15	-	-	6
		ns	0.15	-	-	5,6
Clock to Data Hold Time	tHOLD	UI	0.15	-	-	6
		ns	0.15	-	-	5,6

- Note:
4. When fDSICLK < 125MHz, change auto load NV setting so that it is compliant with THS-PREPARE+THS-ZERO spec.
 5. Minimum tSETUP/tHOLD Time is 0.15UI. This value may change according to DSI transfer rate.
 6. tSETUP/tHOLD Time are measured without HS-TX Jitter.

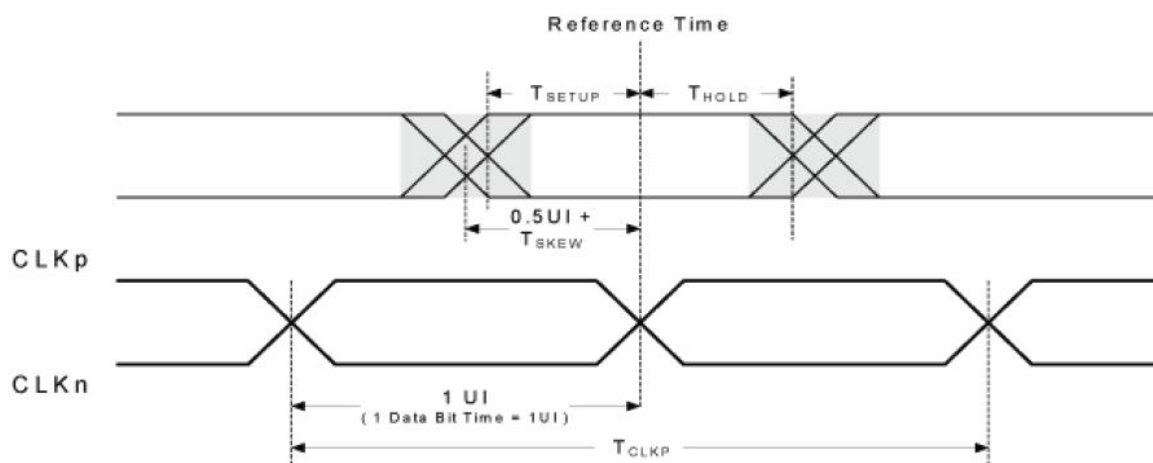
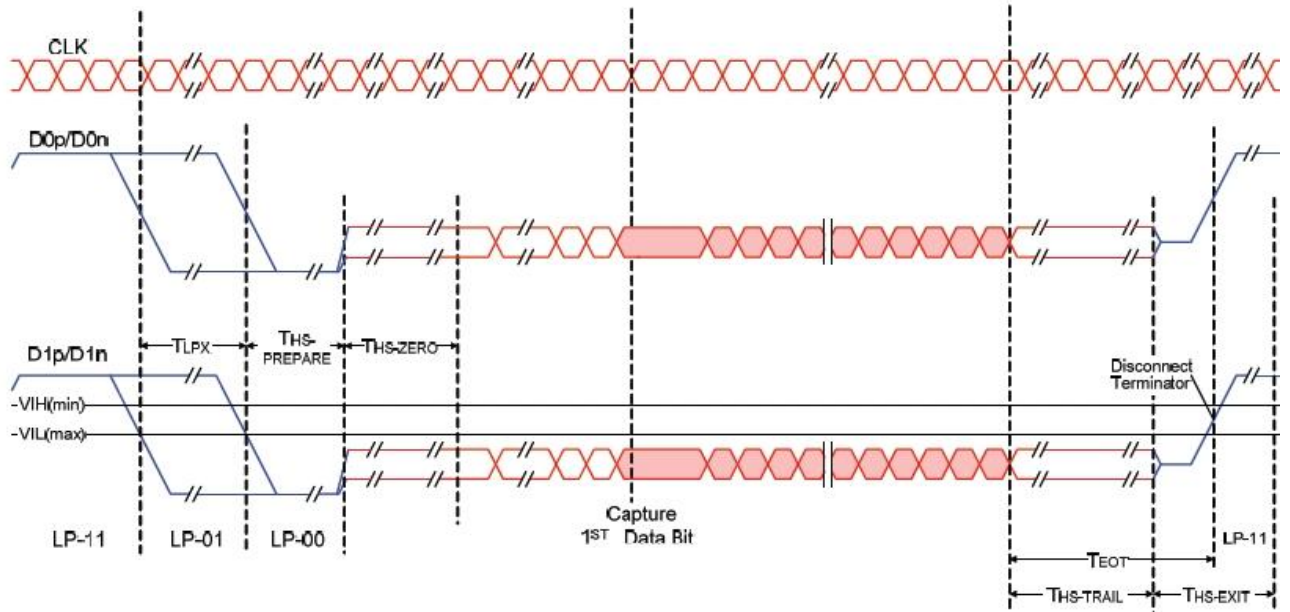


Figure. Data to Clock Timing Definitions

8.3.3 MIPI DSI LP-RX/TX Clock and Data-Clock Specifications

Parameter	Description	Min.	Typ.	Max.	Unit	Note
$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	40 ns+4*UI	-	85 ns+6*UI	ns	
$T_{HS-PREPARE} + T_{HS-ZERO}$	$T_{HS-PREPARE}$ + Time to drive HS-0 before the Sync sequence	145 ns+10*UI	-	-	ns	
$T_{HS-TRAIL}$	Time to drive flipped differential state after last payload data bit of a HS transmission burst	max (n*8*UI, 60 ns+n*4*UI)	-	-	ns	1,2
$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	-	ns	
T_{TA-GO}	Time to drive LP-00 after Turnaround Request	$4 * T_{LPTX}$				
$T_{TA-SURE}$	Time-out before new TX side starts driving	$1 * T_{LPTX}$	-	$2 * T_{LPTX}$		
T_{TA-GET}	Time to drive LP-00 by new TX	$5 * T_{LPTX}$				
T_{LPX}	Length of any Low-Power state period	50	-	-	ns	
Ratio T_{LPX}	Ratio of $T_{LPX(MASTER)}$ / $T_{LPX(SLAVE)}$ between Master and Slave side	2/3	-	3/2		
$T_{CLK-POST}$	Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	60 ns+52UI	-	-	ns	3
$T_{CLK-PREPARE} + T_{CLK-ZERO}$	$T_{CLK-PREPARE}$ + time for lead HS-0 drive period before starting Clock	300	-	-	ns	
$T_{CLK-PRE}$	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	8	-	-	UI	
$T_{CLK-PREPARE}$	Time to drive LP-00 to prepare for HS clock transmission	38	-	95	ns	
$T_{CLK-TRAIL}$	Time to drive HS differential state after last payload clock bit of an HS transmission burst	60	-	-	ns	
T_{EOT}	Time from start of $T_{HS-TRAIL}$ period to start of LP-11 state	-	-	105 ns+n*12*UI		2
T_{LPTX1}	Length of Low-Power TX period in case of using DSI clock	-	48	-	UI	4
T_{LPTX2}	Length of Low-Power TX period in case of using internal OSC clock	-	1/fosc1	-	ns	

- Note:
1. If $a > b$ then $\max(a, b) = a$, otherwise $\max(a, b) = b$
 2. Where $n=1$ for Forward-direction HS mode
 3. The R69429 can work with this specification although the end part of internal process is remained when Clock Lane enter LP-11 and the R69429 can work without the remained process if $t_{CLK-POST}$ is more than 256 UI.
 4. The R69429 uses DSI clock from the Host processor if Clock Lane is active, and internal oscillator clock if Clock Lane is disable. Here, "fosc1" is the frequency of oscillator clock, typical 28MHz.



Note: THS-SYNC: Proper match found for Sync sequence in HS stream, the following bits are payload data.

Figure. HS Data Transmission in Bursts

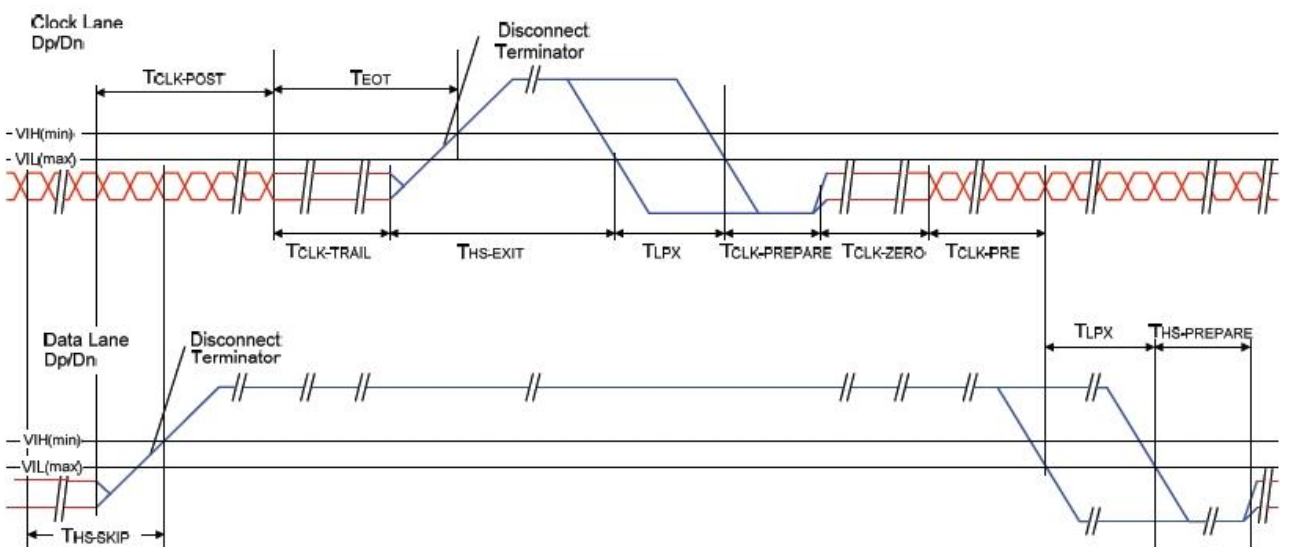


Figure. Switching the Clock Lane between Clock Transmission and LP Mode

8.3.4 ID Code

1. ID Bit Programming

MP (J1)	ID1 (ID1[15:8])	Vendor Code	001	JDI
		Build	01	MP
			000	J1
	ID2 (ID1[7:0])	Reserved	00	-
		Register setting revision	01010	Rev.1.0
	ID3 (ID2[15:8])	Year	-	-
Week code		-	-	
MP (D1)	ID1 (ID1[15:8])	Vendor Code	001	JDI
		Build	01	MP
			001	D1
	ID2 (ID1[7:0])	Reserved	00	-
		Register setting revision	01010	Rev.1.0
	ID3 (ID2[15:8])	Year	-	-
		Week code	-	-

2. Driver IC ID Bit Programming

Command	A1h	D7	D6	D5	D4	D3	D2	D1	D0
1st Parameter	ID1[15:8]	Vendor Code			Reserved		Build		
2nd Parameter	ID1[7:0]	-	Reserved			Register setting revision			
3rd Parameter	ID2[15:8]	Year			Week code				

MP (J1)

Command	A1h	D7	D6	D5	D4	D3	D2	D1	D0	HEX
1st Parameter	ID1[15:8]	0	0	1	0	1	0	0	0	28
2nd Parameter	ID1[7:0]	0	0	0	0	1	0	1	0	0A
3rd Parameter	ID2[15:8]	MP Production year and week code								

MP (D1)

Command	A1h	D7	D6	D5	D4	D3	D2	D1	D0	HEX
1st Parameter	ID1[15:8]	0	0	1	0	1	0	0	1	29
2nd Parameter	ID1[7:0]	0	0	0	0	1	0	1	0	0A
3rd Parameter	ID2[15:8]	MP Production year and week code								

MP Production year and week code

Production week		Year code 01 : 2013 10 : 2014	Week code	ID 3rd Parameter (HEX)
9/9 - 9/15	Week37	01	100101	65
9/16 - 9/22	Week38	01	100110	66
9/23 - 9/29	Week39	01	100111	67
9/30 - 10/6	Week40	01	101000	68
10/7 - 10/13	Week41	01	101001	69
10/14 - 10/20	Week42	01	101010	6A
10/21 - 10/27	Week43	01	101011	6B
10/28 - 11/3	Week44	01	101100	6C
11/4 - 11/10	Week45	01	101101	6D
11/11 - 11/17	Week46	01	101110	6E
11/18 - 11/24	Week47	01	101111	6F
11/25 - 12/1	Week48	01	110000	70
12/2 - 12/8	Week49	01	110001	71
12/9 - 12/15	Week50	01	110010	72
12/16 - 12/22	Week51	01	110011	73
12/23 - 12/29	Week52	01	110100	74
12/30 - 1/5	Week1	10	000001	81
1/6 - 1/12	Week2	10	000010	82

ONLY REFERENCE PURPOSE (No Guarantee)

Technical drawing of a rectangular device, likely a display or sensor module, showing dimensions and labels.

Top View Dimensions:

- Overall width: 200.3 ± 0.3 (SPC-2)
- Upper polarizer width: 196.2 ± 0.25 (FAI-3)
- Active center width: 192 ± 0.03 (FAI-2)
- Active center width (A/A): 100.15
- Right side margin: (2.1) and (4.15)
- Overall height: 132.1 ± 0.3 (SPC-1)
- Upper polarizer height: 123.6 ± 0.25 (FAI-4)
- Active center height: 120 ± 0.03 (FAI-1)
- Active center height (A/A): 63.15
- Bottom margin: (8.95)
- Bottom width: 200.9 ± 0.3 (FAI-8) (Bezel)

Detail A (Scale 3:1):

Detail A shows a cross-section of the device, highlighting the bezel and internal components. Dimensions for Detail A include:

- Top margin: 4.15 ± 0.3
- Top width: (192) (A/A)
- Top width (FAI-5): 2.1 ± 0.35
- Left margin: 3.15 ± 0.3
- Left margin (A/A): (120)
- Left margin (FAI-6): 1.5 ± 0.35

